HARTING	DIN	Signal	female	connector	

IEC 60603-2

max. 20mOhm

min. 10120hm

-55°C ... +125°C

-40°C ... +105°C

min. 1,2 mm each 16-pole max. 15N

48-pole max. 45N

PL 1 acc. to IEC 60603-2

PL 2 acc. to IEC 60603-2

PL 3 acc. to IEC 60603-2

PBT (thermoplastics, glass fiber reinforcement 30%)

PL S4

E102079

Yes Yes

No

RAL 7032 (grey)

IIIa (175 <u><</u> CTI < 400)

UL 94-V0

Copper alloy

Au over Ni

Au over Ni

2

Sn over Ni for solder, Ni for press-in

13, F4

press-in, solder pins

2A at 20°C (see derating diagram)

max. 96

2,54 mm 1000V ٦

40A for type M

30-pole max. 30N

96-pole max. 90N

500 mating cycles

500 mating cycles

400 mating cycles

50 mating cycles

(for press-in connectors)

20-pole max. 20N

64-pole max. 60N

types: B, 2B, 3B, C, 2C, 3C, M female

2



32-pole max. 30N

4

Recommended configuration of plated through holes for press-in termination

In addition to the hot-air-level (HAL), other PCB surfaces are getting more importan Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes.

drilled hole ${\it  extsf{0}}$	I		L
-		╞╼┤	Cu min. 25 µm
finished hole $ ot\!$	-		F
<u>plating (e</u>	.g. Sn)	╺╼┤┤╍	+

6

## Assembly instructions

5

It is highly recommended to use HARTING press-in tools to ensure a reliable pressabout the press-in process.

## Soldering instructions

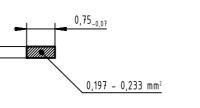
The connectors should be protected when being soldered in a dip, flow or film solde operations or deformed as a result of overheating.

(1) For prototypes and short runs protect the connectors with an industrial adhesive Cover the underside of the connector moulding and the adjacent parts of the pcb as soldering apparatus from damaging the connector. About 140 + 5 mm of the tape sho

(2) For large series a jig is recommended. Its protective cover with a fast action mer soldering apparatus. As an additional protection a foil can be used for covering the

Cross section of solder terminations

0,3±0,01



## Derating diagram acc. to IEC 60512-5 (Current carrying capacity)

General information

Contact spacing

Insulation resistance

Working current

Mating cycles

RoHS - compliant

Insulator material

NFF classification

Contact material

Contact material

Plating termination zone

Plating contact zone II (termination side)

Plating contact zone I

Material group acc. IEC 60664-1

UL file

Leadfree

Material

Color UL classification

Hot plugging

Temperature range

Termination technology

Clearance & creepage distance

Insertion and withdrawal force

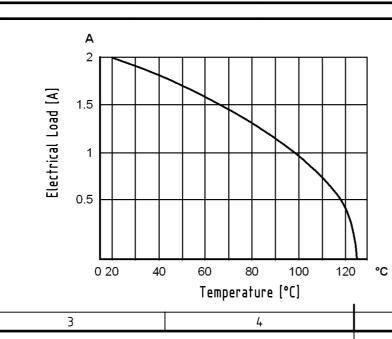
Test voltage Contact resistance

Design No. of contacts

The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.

E The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.

Control and test procedures according to DIN IEC 60512-5



	isions in mm Size DIN A3	Scale 1:1	Free size	e tol.	
All rights	reserved	Created by STORCK		Inspec LEHNE	:ted by RT
Department EC	PD – DE	Title DIN (	Signalo	fom	مام دمة
HARTING Electronics GmbH		— DIN Sig		TEIIIG	
D-32339 Espelkamp		Type DS	Num	<sup>nber</sup> 0	9032
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	7		8	_
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				T A
	Tin plated PCB (HAL)	Drilled hole Ø	1,15±0,025 mm	<u>۱</u>
	acc. to EN 60352-5	Sn	max. 15 µm	
	ļ	plated hole Ø	0,94 - 1,09 mm	
		Drilled hole Ø	1,15±0,025 mm	
	Chemical tin plated PCB	Sn plated belo Ø	min. 0,8µm	
		plated hole Ø Drilled hole Ø	1,00 - 1,10 mm 1,15±0,025 mm	┫┝─
		Ni	3 - 7 µm	
	Gold /Nickel plated PCB	Au	0,05 - 0,12 µm	11
		plated hole Ø	1,00 - 1,10 mm	11
		Drilled hole Ø	1,15±0,025 mm	<b>†</b>
	Silver plated PCB	Ag	0,1 - 0,3 µm	]
		plated hole Ø	1,00 - 1,10 mm	]   E
	Copper plated	Drilled hole Ø	1,15±0,025 mm	
	PCB (OSP)	plated hole Ø	1,00 - 1,10 mm	
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